### INTEGRATED CIRCUITS

## DATA SHEET

# **74LV244**Octal buffer/line driver (3-State)

Product specification Supersedes data of 1997 Feb 19 IC24 Data Handbook





## Octal buffer/line driver (3-State)

74LV244

#### **FEATURES**

- Wide operating voltage: 1.0 to 5.5 V
- Optimized for low voltage applications: 1.0 to 3.6 V
- Accepts TTL input levels between V<sub>CC</sub> = 2.7 V and V<sub>CC</sub> = 3.6 V
- Typical V<sub>OLP</sub> (output ground bounce) < 0.8 V at V<sub>CC</sub> = 3.3 V,  $T_{amb} = 25^{\circ}C$
- Typical V<sub>OHV</sub> (output V<sub>OH</sub> undershoot) > 2 V at V<sub>CC</sub> = 3.3 V,  $T_{amb} = 25^{\circ}C$
- Output capability: bus driver
- I<sub>CC</sub> category: MSI

#### DESCRIPTION

The 74LV244 is a low-voltage Si-gate CMOS device and is pin and function compatible with 74HC/HCT244.

The 74LV244 is an octal non-inverting buffer/line driver with 3-State outputs. The 3-State outputs are controlled by the output enable inputs 10E and 20E. A HIGH on nOE causes the outputs to assume a high impedance OFF-state. The 74LV244 is identical to the 74LV240 but has non-inverting outputs.

#### **QUICK REFERENCE DATA**

GND = 0 V;  $T_{amb} = 25^{\circ}C$ ;  $t_{r} = t_{f} \le 2.5 \text{ ns}$ 

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay 1A <sub>n</sub> to 1Y <sub>n</sub> ; 2A <sub>n</sub> to 2Y <sub>n</sub>	C <sub>L</sub> = 15 pF; V <sub>CC</sub> = 3.3 V	8.0	ns
C <sub>I</sub>	Input capacitance		3.5	pF
C <sub>PD</sub>	Power dissipation capacitance per buffer	$V_{CC} = 3.3 \text{ V}$ $V_I = \text{GND to } V_{CC}^1$	35	pF

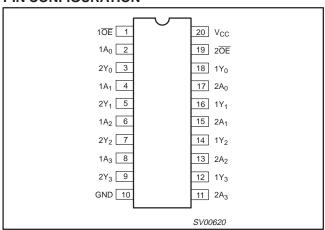
#### NOTE:

- 1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ )
  - $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$  where:
  - f<sub>i</sub> = input frequency in MHz; C<sub>L</sub> = output load capacitance in pF;
  - $f_0$  = output frequency in MHz;  $V_{CC}$  = supply voltage in V;
  - $\sum (C_L \times V_{CC}^2 \times f_0) = \text{sum of the outputs.}$

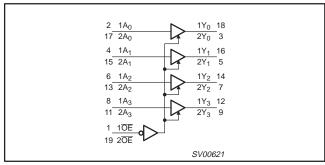
#### ORDERING INFORMATION

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PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
20-Pin Plastic DIL	–40°C to +125°C	74LV244 N	74LV244 N	SOT146-1
20-Pin Plastic SO	-40°C to +125°C	74LV244 D	74LV244 D	SOT163-1
20-Pin Plastic SSOP Type II	–40°C to +125°C	74LV244 DB	74LV244 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +125°C	74LV244 PW	74LV244PW DH	SOT360-1

#### **PIN CONFIGURATION**



#### LOGIC SYMBOL



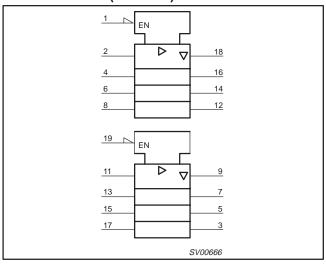
## Octal buffer/line driver (3-State)

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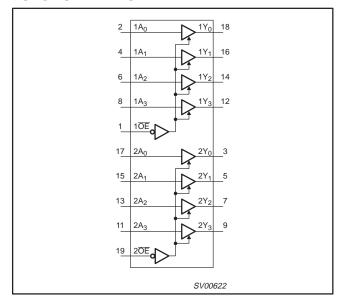
#### **PIN DESCRIPTION**

PIN NUMBER	SYMBOL	FUNCTION
1 1 <del>OE</del>		Output enable input (active LOW)
2, 4, 6, 8 1A <sub>0</sub> to 1A <sub>3</sub>		Data inputs
3, 5, 7, 9	2Y <sub>0</sub> to 2Y <sub>3</sub>	Bus outputs
10	GND	Ground (0 V)
17, 15, 13, 11	2A <sub>0</sub> to 2A <sub>3</sub>	Data inputs
18, 16, 14, 12	1Y <sub>0</sub> to 1Y <sub>3</sub>	Bus outputs
19	2 <del>OE</del>	Output enable input (active LOW)
20 V <sub>CC</sub>		Positive supply voltage

#### LOGIC SYMBOL (IEEE/IEC)



#### **FUNCTIONAL DIAGRAM**



#### **FUNCTION TABLE**

INP	OUTPUT	
nOE	nA <sub>n</sub>	nY <sub>n</sub>
L	L	L
L	Н	Н
Н	Х	Z

#### NOTES:

H = HIGH voltage level
L = LOW voltage level
X = don't care L = X = Z =

high impedance OFF-state

## Octal buffer/line driver (3-State)

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#### RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>CC</sub>	DC supply voltage	See Note 1	1.0	3.3	5.5	V
VI	Input voltage		0	-	V <sub>CC</sub>	V
Vo	Output voltage		0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	Operating ambient temperature range in free air	See DC and AC characteristics	-40 -40		+85 +125	°C
t <sub>r</sub> , t <sub>f</sub>	Input rise and fall times	$\begin{array}{c} V_{CC} = 1.0V \text{ to } 2.0V \\ V_{CC} = 2.0V \text{ to } 2.7V \\ V_{CC} = 2.7V \text{ to } 3.6V \\ V_{CC} = 3.6V \text{ to } 5.5V \end{array}$		- - -	500 200 100 50	ns/V

#### NOTE

#### **ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>**

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +7.0	V
± I <sub>IK</sub>	DC input diode current	$V_{I} < -0.5 \text{ or } V_{I} > V_{CC} + 0.5V$	20	mA
± I <sub>OK</sub>	DC output diode current	$V_{O} < -0.5 \text{ or } V_{O} > V_{CC} + 0.5V$	50	mA
±I <sub>O</sub>	DC output source or sink current  – bus driver outputs	$-0.5V < V_O < V_{CC} + 0.5V$	35	mA
± I <sub>GND</sub> , ± I <sub>CC</sub>	DC V <sub>CC</sub> or GND current for types with – bus driver outputs		70	mA
T <sub>stg</sub>	Storage temperature range		-65 to +150	°C
P <sub>TOT</sub>	Power dissipation per package  – plastic DIL  – plastic mini-pack (SO)  – plastic shrink mini-pack (SSOP and TSSOP)	for temperature range: -40 to +125°C above +70°C derate linearly with 12 mW/K above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	750 500 400	mW

#### NOTES

<sup>1.</sup> The LV is guaranteed to function down to  $V_{CC}$  = 1.0V (input levels GND or  $V_{CC}$ ); DC characteristics are guaranteed from  $V_{CC}$  = 1.2V to  $V_{CC}$  = 5.5V.

Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>2.</sup> The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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#### DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	-40	°C to +8	5°C	-40°C to	+125°C	UNIT
			MIN	TYP <sup>1</sup>	MAX	MIN	MAX	
		V <sub>CC</sub> = 1.2V	0.9			0.9		
V	HIGH level Input	V <sub>CC</sub> = 2.0V	1.4			1.4		] <sub>v</sub>
$V_{IH}$	voltage	V <sub>CC</sub> = 2.7 to 3.6V	2.0			2.0		]
		$V_{CC} = 4.5 \text{ to } 5.5 \text{V}$	0.7 * V <sub>CC</sub>			0.7 * V <sub>CC</sub>		
		V <sub>CC</sub> = 1.2V			0.3		0.3	
$V_{IL}$	LOW level Input	V <sub>CC</sub> = 2.0V			0.6		0.6	V
۷IL	voltage	$V_{CC} = 2.7 \text{ to } 3.6 \text{V}$			0.8		0.8	] `
		$V_{CC} = 4.5 \text{ to } 5.5$			0.3 * V <sub>CC</sub>		0.3 * V <sub>CC</sub>	
		$V_{CC} = 1.2V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $-I_O = 100\mu A$		1.2				
	LUCIUS STATE	$V_{CC} = 2.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $-I_O = 100\mu A$	1.8	2.0		1.8		
$V_{OH}$	HIGH level output voltage; all outputs	$V_{CC} = 2.7V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $-I_O = 100\mu A$	2.5	2.7		2.5		V
		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $-I_O = 100\mu A$	2.8	3.0		2.8		
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 100 \mu A$	4.3	4.5		4.3		
M	HIGH level output voltage; BUS driver	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 8\text{mA}$	2.40	2.82		2.20		
V <sub>OH</sub>	outputs	$V_{CC} = 4.5V$ ; $V_I = V_{IH}$ or $V_{IL;} -I_O = 16$ mA	3.60	4.20		3.50		1 '
		$V_{CC} = 1.2V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 100\mu A$		0				
		$V_{CC} = 2.0V; V_I = V_{IH} \text{ or } V_{IL;} I_O = 100 \mu A$		0	0.2		0.2	
$V_{OL}$	LOW level output voltage; all outputs	$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	V
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		0	0.2		0.2	
		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL;} I_O = 100 \mu A$		0	0.2		0.2	
V <sub>OL</sub>	LOW level output voltage; BUS driver	$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 8mA$		0.25	0.40		0.50	V
VOL	outputs	$V_{CC} = 4.5V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 16$ mA		0.35	0.55		0.65	ľ
I <sub>I</sub>	Input leakage current	$V_{CC} = 5.5V$ ; $V_I = V_{CC}$ or GND			1.0		1.0	μА
I <sub>OZ</sub>	3-State output OFF-state current	$V_{CC}$ = 3.6V; $V_{I}$ = $V_{IH}$ or $V_{IL}$ ; $V_{O}$ = $V_{CC}$ or GND			5		10	μΑ
I <sub>CC</sub>	Quiescent supply current; MSI	$V_{CC} = 5.5V; V_{I} = V_{CC} \text{ or GND}; I_{O} = 0$			20.0		160	μА
Δl <sub>CC</sub>	Additional quiescent supply current per input	$V_{CC} = 2.7V \text{ to } 3.6V; V_I = V_{CC} - 0.6V$			500		850	μΑ

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#### NOTE:

<sup>1.</sup> All typical values are measured at  $T_{amb} = 25^{\circ}C$ .

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#### **AC CHARACTERISTICS**

GND = 0V;  $t_r = t_f \le 2.5 \text{ns}$ ;  $C_L = 50 \text{pF}$ ;  $R_L = 1 \text{K}\Omega$ 

			CONDITION			LIMITS			
SYMBOL	PARAMETER	WAVEFORM	CONDITION		40 to +85 °	.C	-40 to	+125 °C	UNIT
			V <sub>CC</sub> (V)	MIN	TYP <sup>1</sup>	MAX	MIN	MAX	
			1.2		50				
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay		2.0		17	24		31	
	1A <sub>n</sub> to 1Y <sub>n</sub> ;	Figures 1, 2	2.7		13	17		23	ns
	2A <sub>n</sub> to 2Y <sub>n</sub>		3.0 to 3.6		92	14		18	
			4.5 to 5.5			12		15	
	3-State output enable time 10E to 1Y <sub>n</sub> ;	Figures 2, 3	1.2		65				
			2.0		22	39		49	
t <sub>PZH</sub> /t <sub>PZL</sub>			2.7		16	29		36	ns
	2OE to 2Yn		3.0 to 3.6		12 <sup>2</sup>	23		29	
			4.5 to 5.5			19		24	
			1.2		60				
	3-State output disable time		2.0		22	34		43	
t <sub>PHZ</sub> /t <sub>PLZ</sub>	1 <del>OE</del> to 1Y <sub>n</sub> ;	Figures 2, 3	2.7		17	24		32	ns
	2OE to 2Y <sub>n</sub>		3.0 to 3.6		13 <sup>2</sup>	21		26	
			4.5 to 5.5			16		19	

#### NOTES:

- 1. Unless otherwise stated, all typical values are measured at  $T_{amb} = 25$ °C.
- 2. Typical values are measured at  $V_{CC} = 3.3 \text{ V}$ .

#### **AC WAVEFORMS**

 $V_{M}$  = 1.5 V at  $V_{CC} \geq$  2.7 V and  $\leq$  3.6 V

 $V_M = 0.5 \times V_{CC}$  at  $V_{CC} < 2.7$  V and  $\ge 4.5$  V

 $\rm V_{OL}$  and  $\rm V_{OH}$  are the typical output voltage drop that occur with the output load.

 $V_X = V_{OL} + 0.3 \text{ V}$  at  $V_{CC} \ge 2.7 \text{ V}$  and  $\le 3.6 \text{ V}$ 

 $V_X = V_{OL} + 0.1 \times V_{CC}$  at  $V_{CC} < 2.7$  V and  $\ge 4.5$  V

 $V_Y = V_{OH} - 0.3 \text{ V at } V_{CC} \ge 2.7 \text{V and } \le 3.6 \text{ V}$ 

 $V_Y = V_{OH} - 0.1 \times V_{CC}$  at  $V_{CC} < 2.7$  V and  $\ge 4.5$  V

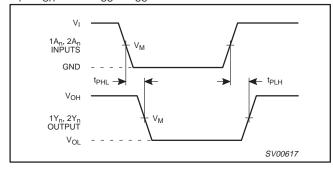


Figure 1. Input  $(1A_n, 2A_n)$  to output  $(1Y_n, 2Y_n)$  propagation delays.

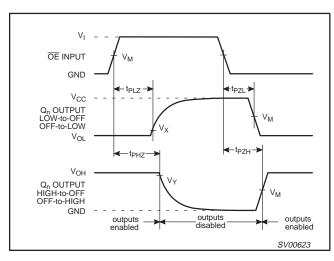


Figure 2. 3-State enable and disable times.

## Octal buffer/line driver (3-State)

74LV244

#### **TEST CIRCUIT**

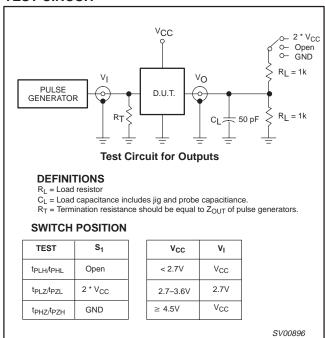
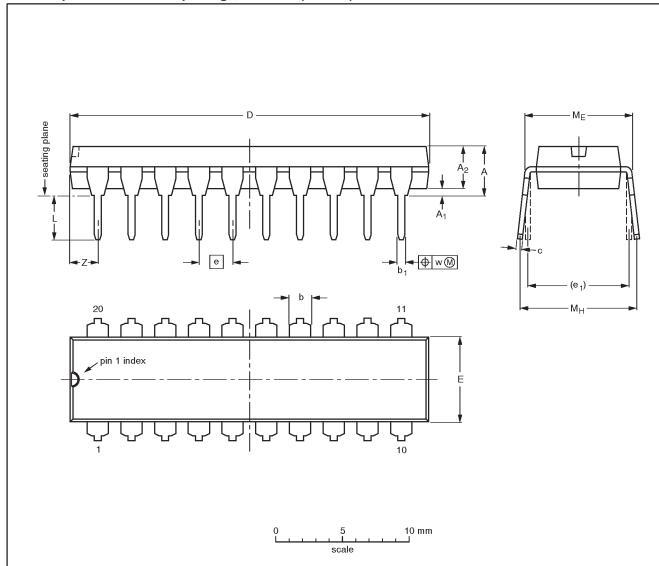


Figure 3. Load circuitry for switching times.

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## DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

#### Note

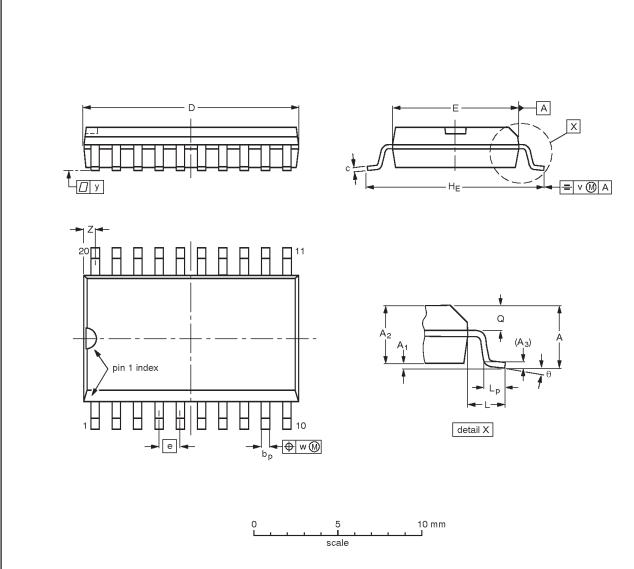
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE REFERENCES				EUROPEAN	ISSUE DATE		
	VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
	SOT146-1			SC603		<del>92-11-17</del> 95-05-24	

74LV244

#### SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	bp	O	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	٧	w	у	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	0°

#### Note

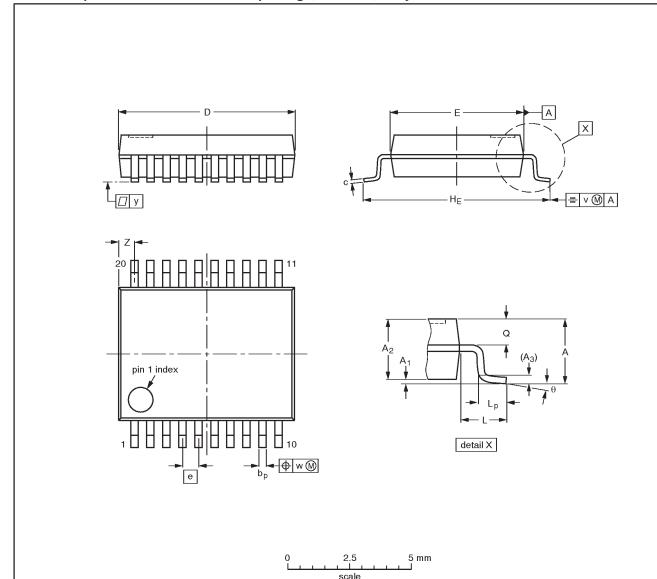
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC JEDEC EIAJ				PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC				<del>-92-11-17</del> 95-01-24	

74LV244

#### SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



#### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	bр	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Ø	v	w	у	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

#### Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

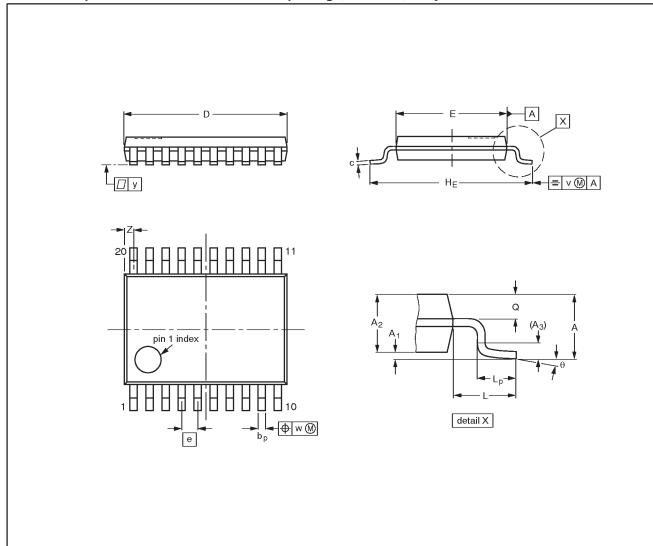
OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1550E DATE	
SOT339-1		MO-150AE				<del>93-09-08</del> 95-02-04	

## Octal buffer/line driver (3-State)

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TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



#### 0 2.5 5 mm scale

#### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	рb	С	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

#### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT360-1		MO-153AC				<del>-93-06-16</del> 95-02-04

## Octal buffer/line driver (3-State)

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DEFINITIONS							
Data Sheet Identification	Product Status	Definition					
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.					
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